

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|-------|--|--|------------------|---------|------------------|
| L1 | 41691 | substrate with ((dielectric insulat\$3) near (layer film)) with ((metal conduct\$3) near (layer film)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/08/17 10:56 |
| L2 | 92 | 1 and ((LED (light adj emit\$4)) near (die\$1 chip\$1)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/08/17 10:56 |
| L3 | 82 | 2 and (via\$1 open\$3 hole\$1 recess\$2) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT ; IBM_TDB | OR | ON | 2005/08/17 10:57 |
| L4 | 215 | substrate AND ((dielectric insulat\$3) near (layer film)) AND ((metal conduct\$3) near (layer film)) AND ((LED (light adj emit\$4)) near (die\$1 chip\$1)) AND (via\$1 open\$3 hole\$1 recess\$2).CLM. | US-PGPUB; USPAT | OR | ON | 2005/08/17 10:58 |
| L5 | 0 | illuminat\$3 AND substrate AND (first near (surface\$1 side\$1)) AND (second near (surface\$1 side\$1)) AND ((dielectric insulat\$3) near (layer film)) AND ((metal conduct\$3) near (layer film)) AND ((LED (light adj emit\$4)) near (die\$1 chip\$1)) AND (via\$1 open\$3 hole\$1 recess\$2) AND (electrical\$2 near thermal\$2 near connect\$3).CLM. | US-PGPUB; USPAT | OR | ON | 2005/08/17 11:02 |
| L6 | 0 | substrate AND (first near (surface\$1 side\$1)) AND (second near (surface\$1 side\$1)) AND ((dielectric insulat\$3) near (layer film)) AND ((metal conduct\$3) near (layer film)) AND ((LED (light adj emit\$4)) near (die\$1 chip\$1)) AND (via\$1 open\$3 hole\$1 recess\$2) AND (electrical\$2 near thermal\$2 near connect\$3).CLM. | US-PGPUB; USPAT | OR | ON | 2005/08/17 11:02 |